Application Report

Bluetooth® Low Energy – Missing Length Check for UNPI Packets Over SPI on CC1350 and CC26x0 Devices

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Summary

A local attacker able to interfere with the physical serial peripheral interface (SPI) bus between the host and the network processor may send a malformed uniformed network processor interface (UNPI) packet that can corrupt dynamic memory in the host processor, thus potentially achieving code execution.

CVSS base score: 7.6

CVSS vector: https://www.first.org/cvss/calculator/3.1#CVSS:3.1/AV:P/AC:L/PR:N/UI:N/S:C/C:H/I:H/A:H

Affected products and versions

- CC1350 SDK, BLE-STACK (SDK v4.10.01 and prior versions)
- CC26x0 BLE-STACK (v2.2.4 and prior versions)

Potentially impacted features

The potential vulnerability can impact *Bluetooth*® Low Energy devices running affected SDK versions that have configured the devices to run in network processor mode and uses UNPI with SPI transport layer as the serial interface between the *Bluetooth* Low Energy device and the external host processor.

Suggested mitigations

The following SDK releases address the potential vulnerability:

Affected SDK	SDK version with mitigations	SDK releases with mitigations
CC13x0 SDK, BLE-STACK	4.10.02	25-Aug-2020
BLE-STACK (support for CC2640 and CC2650)	BLE-STACK v2.2.5	31-Aug-2020

Acknowledgment

- Ruben Santamarta, IOActive

Revision history

- Version 1.0 initial publication

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